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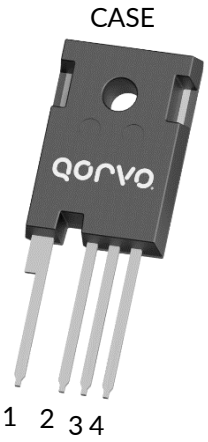
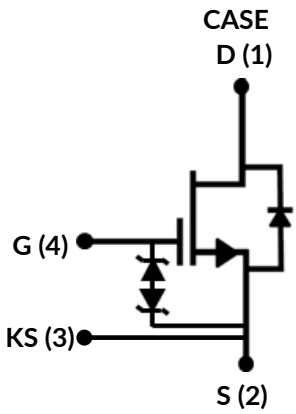
DATASHEET

UF4SC120009K4SH





Part Number	Package	Marking
UF4SC120009K4SH	TO-247-4L HV	UF4SC120009K4SH

RoHS COMPLIANT | Pb LEAD FREE | HF HALOGEN FREE

Silicon Carbide (SiC) Cascode JFET - EliteSiC, Power N-Channel, TO-247-4L, 1200 V, 9.1 mohm

Rev. B, January 2025

Description

The UF4SC120009K4SH is a 1200V, 9.1mΩ G4 SiC FET. It is based on a unique 'cascode' circuit configuration, in which a normally-on SiC JFET is co-packaged with a Si MOSFET to produce a normally-off SiC FET device. The device's standard gate-drive characteristics allows use of off-the-shelf gate drivers hence requiring minimal re-design when replacing Si IGBTs, Si superjunction devices or SiC MOSFETs. Available in the TO-247-4L HV package, this device exhibits ultra-low gate charge and exceptional reverse recovery characteristics, making it ideal for switching inductive loads and any application requiring standard gate drive.

Features

- On-resistance $R_{DS(on)}$: 9.1mΩ (typ)
- Operating temperature: 175°C (max)
- Excellent reverse recovery: Q_{rr} = 615nC
- Low body diode V_{FSD}: 1.09V
- Low gate charge: Q_G = 168nC
- Threshold voltage $V_{G(th)}$: 4.7V (typ) allowing 0 to 15V drive
- Low intrinsic capacitance
- Kelvin source pin for optimized switching performance
- HV package with 8mm D-S creepage distance
- ESD protected: HBM class 2 and CDM class C3
- AECQ Qualified

Typical applications

- EV charging
- PV inverters
- Switch mode power supplies
- Power factor correction modules
- Motor drives
- Induction heating

Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units
Drain-source voltage	V_{DS}		1200	V
Gate-source voltage	V_{GS}	DC	-20 to +20	V
		AC (f > 1Hz)	-25 to +25	V
Continuous drain current [1]	I_D	T_C <100°C	120	A
Pulsed drain current [2]	I_{DM}	T_C = 25°C	550	A
Single pulsed avalanche energy [3]	E_{AS}	L=15mH, I_{AS} =6.5A	317	mJ
SiC FET dv/dt ruggedness	dv/dt	$V_{DS} \leq$ 800V	150	V/ns
Power dissipation	P_{tot}	T_C = 25°C	750	W
Maximum junction temperature	$T_{J,max}$		175	°C
Operating and storage temperature	T_J, T_{STG}		-55 to 175	°C
Max. lead temperature for soldering, 1/8" from case for 5 seconds	T_L		250	°C

1. Limited by by bondwires
2. Pulse width t_p limited by $T_{J,max}$
3. Starting T_J = 25°C

Thermal Characteristics

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Thermal resistance, junction-to-case	$R_{\theta JC}$			0.15	0.20	°C/W

Electrical Characteristics (T_J = +25°C unless otherwise specified)

Typical Performance - Static

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Drain-source breakdown voltage	BV_{DS}	V_{GS}=0V, I_D=1mA	1200			V
Total drain leakage current	I_{DSS}	V_{DS}=1200V, V_{GS}=0V, T_J=25°C		5	300	µA
		V_{DS}=1200V, V_{GS}=0V, T_J=175°C		56		
Total gate leakage current	I_{GSS}	V_{DS}=0V, T_J=25°C, V_{GS}=-20V / +20V		6	20	µA
Drain-source on-resistance	$R_{DS(on)}$	V_{GS}=12V, I_D=80A, T_J=25°C		9.1	10.6	mΩ
		V_{GS}=12V, I_D=80A, T_J=125°C		16.9		
		V_{GS}=12V, I_D=80A, T_J=175°C		23.3		
Gate threshold voltage	$V_{G(th)}$	V_{DS}=5V, I_D=10mA	4	4.7	6	V
Gate resistance	R_G	f=1MHz, open drain		0.8	1.5	Ω

Typical Performance - Reverse Diode

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Diode continuous forward current [1]	I_S	T_C < 100°C			120	A
Diode pulse current [2]	$I_{S,pulse}$	T_C=25°C			550	A
Forward voltage	V_{FSD}	V_{GS}=0V, I_S=40A, T_J=25°C		1.09	1.45	V
		V_{GS}=0V, I_S=40A, T_J=175°C		1.31		
Reverse recovery charge	Q_{rr}	V_{DS}=800V, I_S=80A, V_{GS}=0V, R_{G_EXT}=2Ω di/dt=2600A/µs, T_J=25°C		615		nC
Reverse recovery time	t_{rr}			48		ns
Reverse recovery charge	Q_{rr}	V_{DS}=800V, I_S=80A, V_{GS}=0V, R_{G_EXT}=2Ω di/dt=2600A/µs, T_J=150°C		724		nC
Reverse recovery time	t_{rr}			55		ns

Typical Performance - Dynamic

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Input capacitance	C_{iss}	V_{DS}=800V, V_{GS}=0V f=100kHz		7218		pF
Output capacitance	C_{oss}			204		
Reverse transfer capacitance	C_{rss}			0.2		
Effective output capacitance, energy related	$C_{oss(er)}$	V_{DS}=0V to 800V, V_{GS}=0V		265		pF
Effective output capacitance, time related	$C_{oss(tr)}$	V_{DS}=0V to 800V, V_{GS}=0V		528		pF
C_{OSS} stored energy	E_{oss}	V_{DS}=800V, V_{GS}=0V		85		µJ
Total gate charge	Q_G	V_{DS}=800V, I_D=80A, V_{GS} = 0V to 15V		168		nC
Gate-drain charge	Q_{GD}			28		
Gate-source charge	Q_{GS}			50		
Turn-on delay time	$t_{d(on)}$	Notes 4 and 5, V_{DS}=800V, I_D=80A, Gate Driver =0V to +15V, $R_{G,EXT}$=2Ω, inductive Load, FWD: same device with V_{GS} = 0V and R_G = 2Ω, RC snubber: R_S=5Ω and C_S=440pF, T_J=25°C		40		ns
Rise time	t_r			37		
Turn-off delay time	$t_{d(off)}$			81		
Fall time	t_f			16		
Turn-on energy including R_S energy	E_{ON}			1656		µJ
Turn-off energy including R_S energy	E_{OFF}			255		
Total switching energy	E_{TOTAL}			1911		
Snubber R_S energy during turn-on	E_{RS_ON}			19.5		
Snubber R_S energy during turn-off	E_{RS_OFF}			76.5		
Turn-on delay time	$t_{d(on)}$	Notes 4 and 5, V_{DS}=800V, I_D=80A, Gate Driver =0V to +15V, $R_{G,EXT}$=2Ω, inductive Load, FWD: same device with V_{GS} = 0V and R_G = 2Ω, RC snubber: R_S=5Ω and C_S=440pF, T_J=150°C		36		ns
Rise time	t_r			42		
Turn-off delay time	$t_{d(off)}$			85		
Fall time	t_f			18		
Turn-on energy including R_S energy	E_{ON}			1940		µJ
Turn-off energy including R_S energy	E_{OFF}			283		
Total switching energy	E_{TOTAL}			2223		
Snubber R_S energy during turn-on	E_{RS_ON}			18		
Snubber R_S energy during turn-off	E_{RS_OFF}			71		

4. Measured with the switching test circuit in Figure 26.

5. In this table, the switching energies (turn-on energy, turn-off energy and total energy) presented include the device RC snubber energy losses.

Typical Performance - Dynamic (continued)

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Turn-on delay time	$t_{d(on)}$	Notes 5 and 6, V_{DS}=800V, I_D=80A, Gate Driver =0V to +15V, $R_{G,EXT}$=2Ω, inductive Load, FWD: UJ3D1250K2, RC snubber: R_S=5Ω and C_S=440pF, T_J=25°C		40		ns
Rise time	t_r			30		
Turn-off delay time	$t_{d(off)}$			81		
Fall time	t_f			13		
Turn-on energy including R_S energy	E_{ON}			918		µJ
Turn-off energy including R_S energy	E_{OFF}			250		
Total switching energy	E_{TOTAL}			1168		
Snubber R_S energy during turn-on	E_{RS_ON}			18		
Snubber R_S energy during turn-off	E_{RS_OFF}			113		
Turn-on delay time	$t_{d(on)}$	Notes 5 and 6, V_{DS}=800V, I_D=80A, Gate Driver =0V to +15V, $R_{G,EXT}$=2Ω, inductive Load, FWD: UJ3D1250K2, RC snubber: R_S=5Ω and C_S=440pF, T_J=150°C		36		ns
Rise time	t_r			34		
Turn-off delay time	$t_{d(off)}$			85		
Fall time	t_f			14		
Turn-on energy including R_S energy	E_{ON}			1040		µJ
Turn-off energy including R_S energy	E_{OFF}			280		
Total switching energy	E_{TOTAL}			1320		
Snubber R_S energy during turn-on	E_{RS_ON}			16.5		
Snubber R_S energy during turn-off	E_{RS_OFF}			110		

6. Measured with the switching test circuit in Figure 26 where the high-side switch Q1 is replaced with the diode and no RC snubber is applied for the diode.

Typical Performance Diagrams

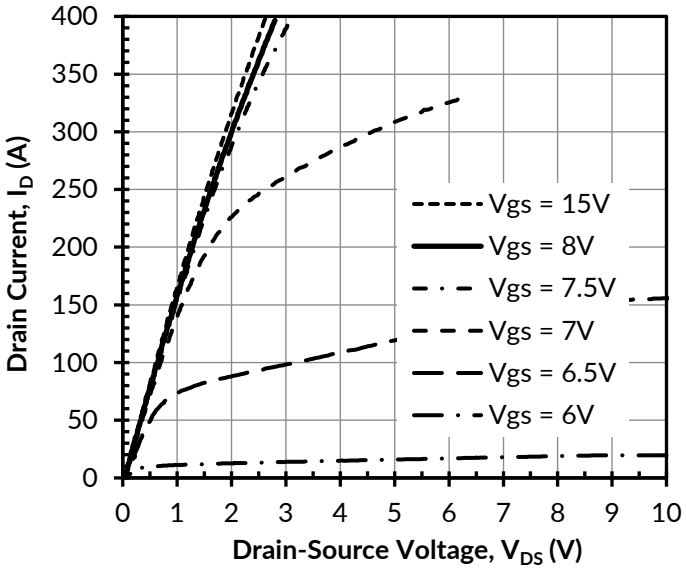


Figure 1. Typical output characteristics at T_J = - 55°C, tp < 250µs

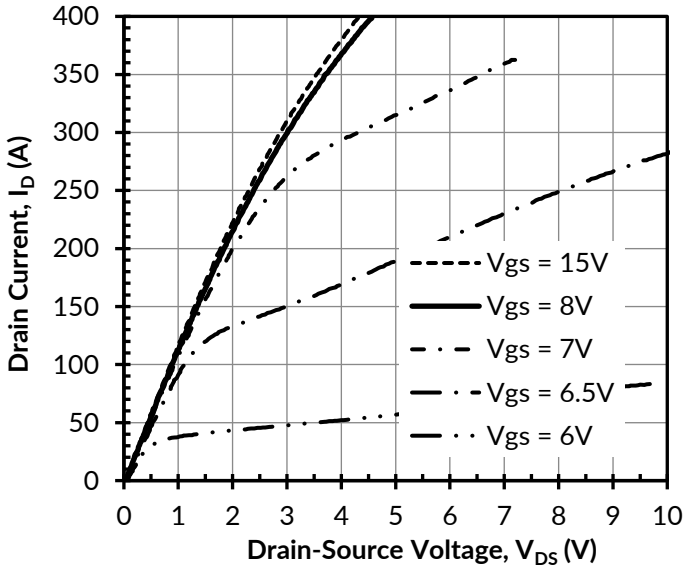


Figure 2. Typical output characteristics at T_J = 25°C, tp < 250µs

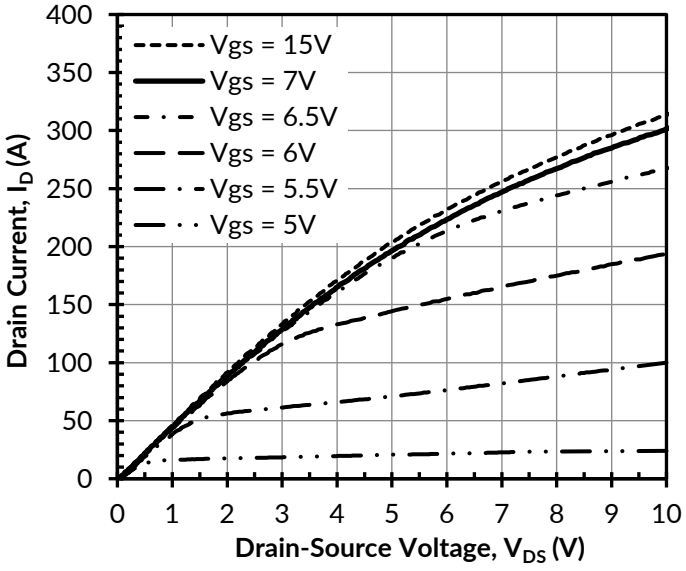


Figure 3. Typical output characteristics at T_J = 175°C, tp < 250µs

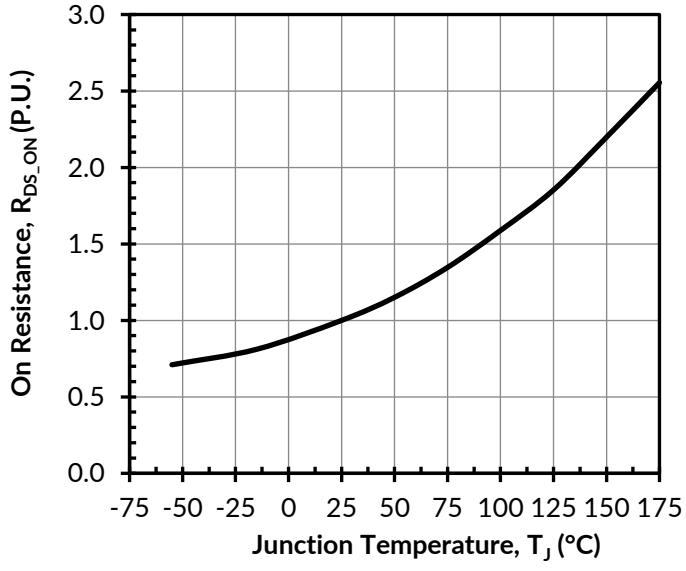


Figure 4. Normalized on-resistance vs. temperature at V_{GS} = 12V and I_D = 80A

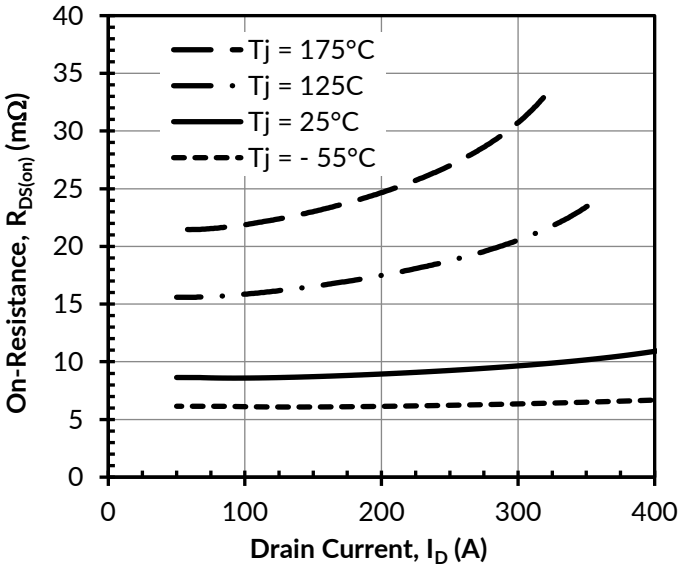


Figure 5. Typical drain-source on-resistances at V_{GS} = 12V

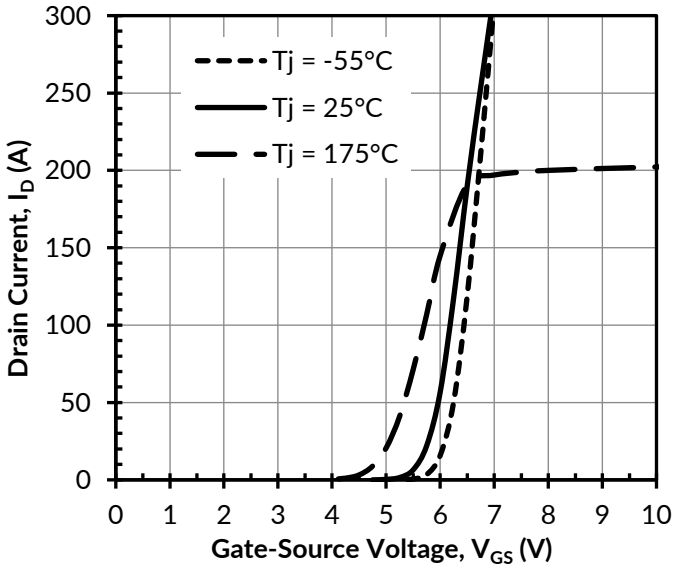


Figure 6. Typical transfer characteristics at V_{DS} = 5V

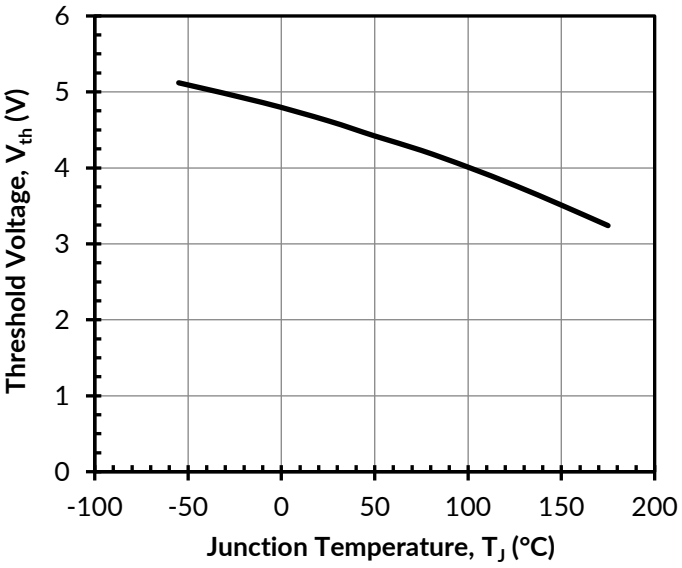


Figure 7. Threshold voltage vs. junction temperature at V_{DS} = 5V and I_D = 10mA

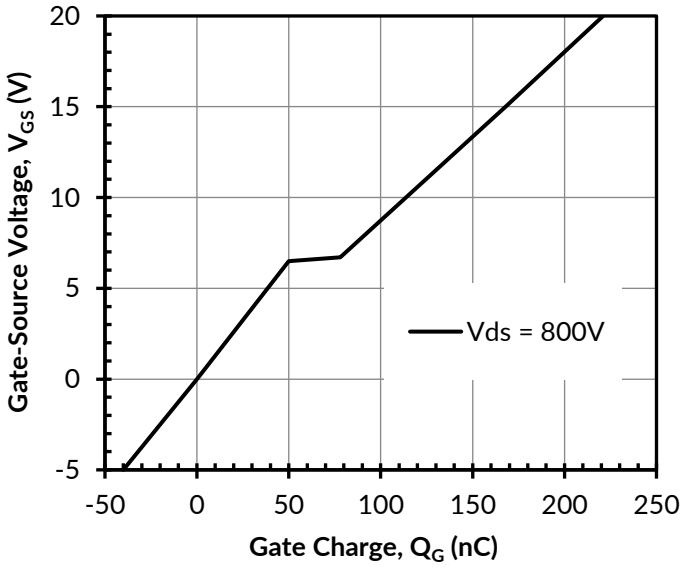


Figure 8. Typical gate charge at I_D = 80A

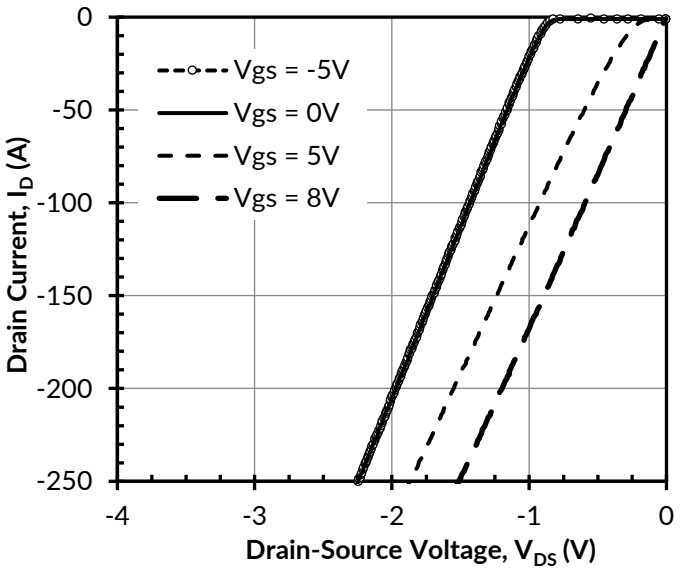


Figure 9. 3rd quadrant characteristics at T_J = -55°C

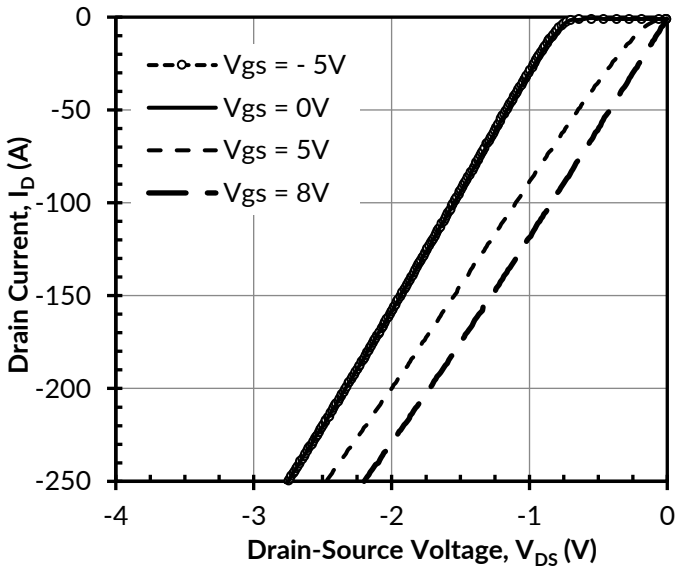


Figure 10. 3rd quadrant characteristics at T_J = 25°C

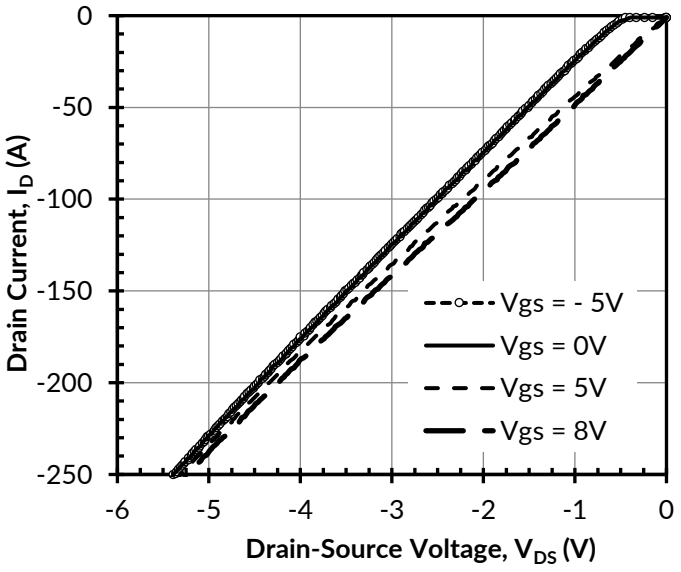


Figure 11. 3rd quadrant characteristics at T_J = 175°C

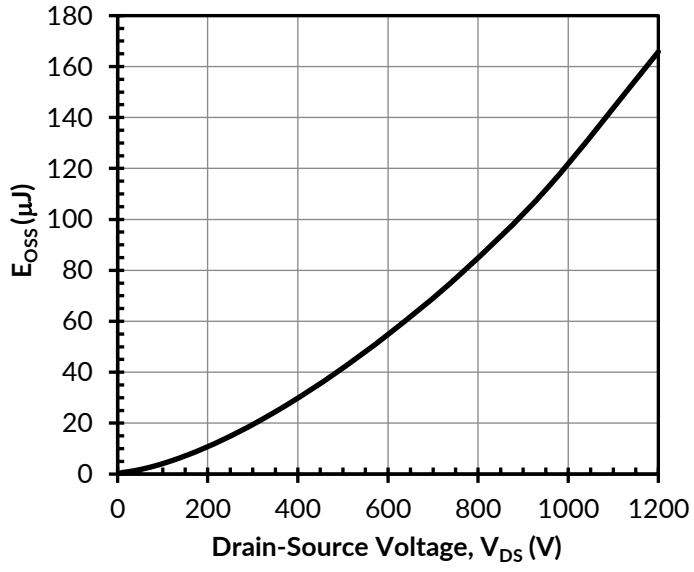


Figure 12. Typical stored energy in C_{OSS} at V_{GS} = 0V

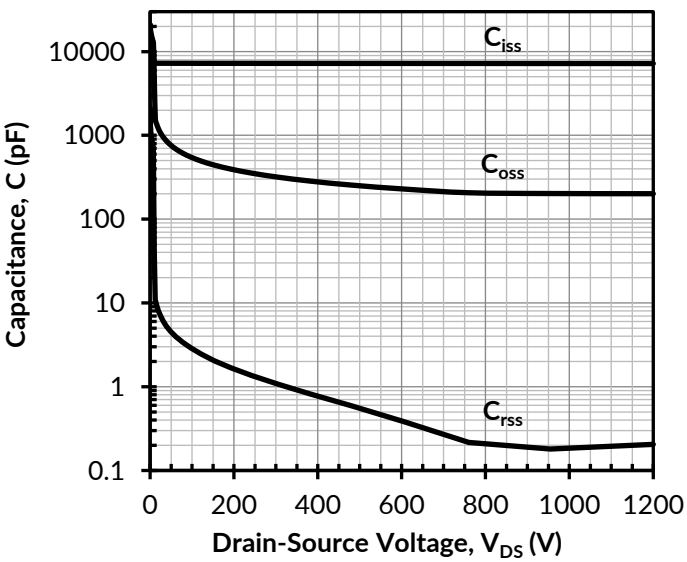


Figure 13. Typical capacitances at f = 100kHz and V_{GS} = 0V

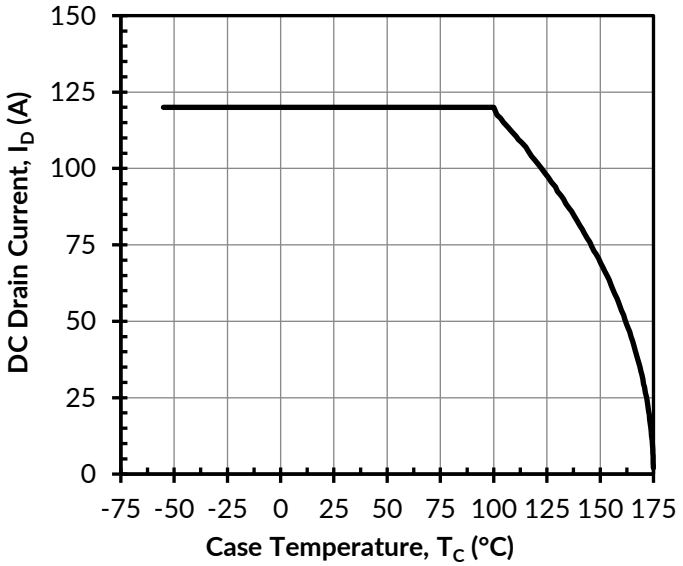


Figure 14. DC drain current derating

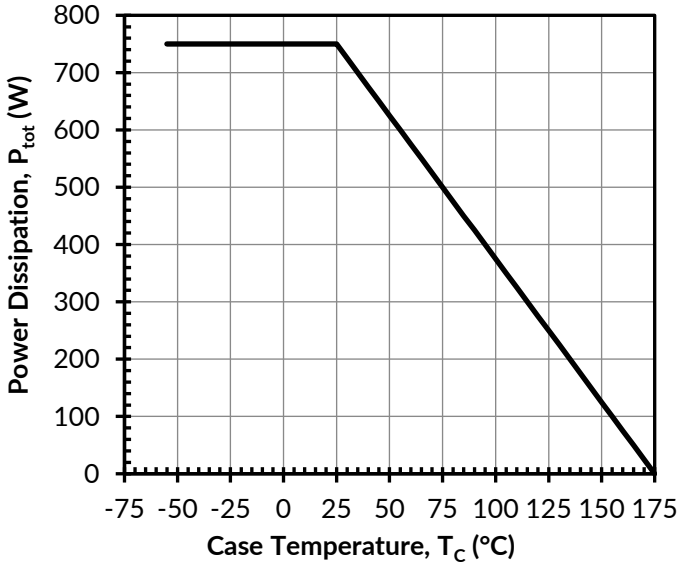


Figure 15. Total power dissipation

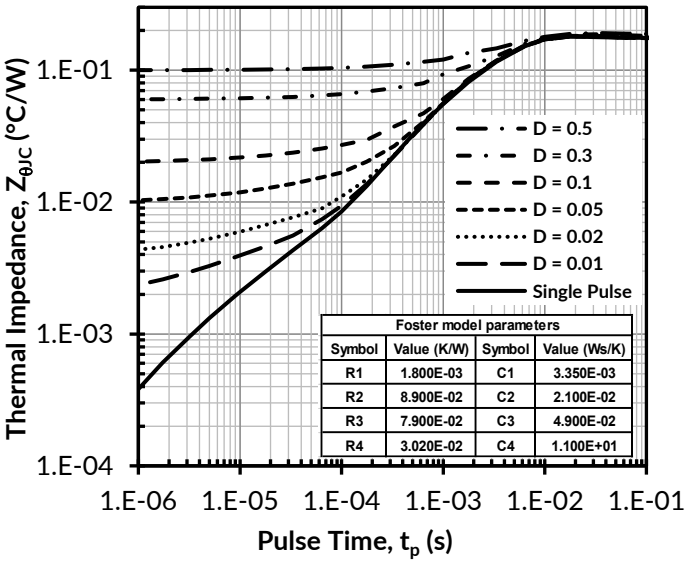


Figure 16. Maximum transient thermal impedance

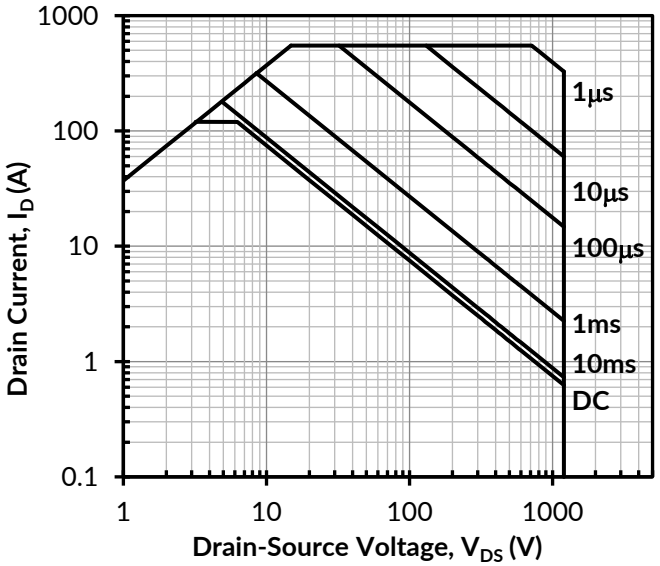


Figure 17. Safe operation area at T_C = 25°C, D = 0, Parameter t_p

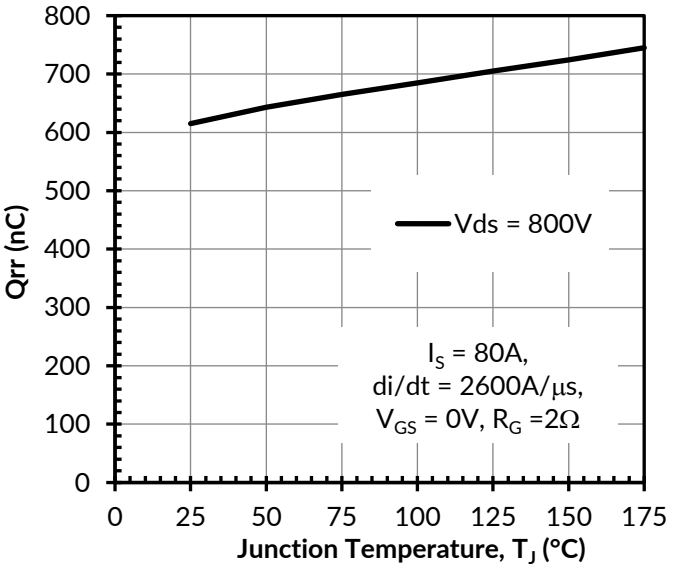


Figure 18. Reverse recovery charge Qrr vs. junction temperature

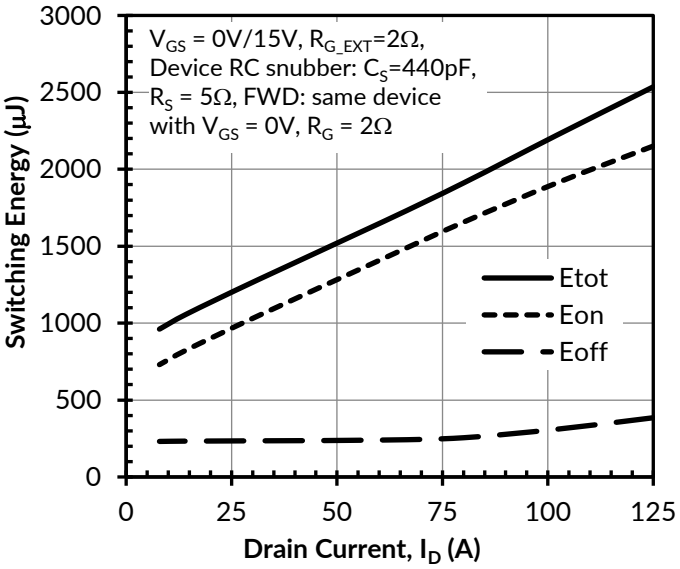


Figure 19. Clamped inductive switching energy vs. drain current at V_{DS} = 800V and T_J = 25°C

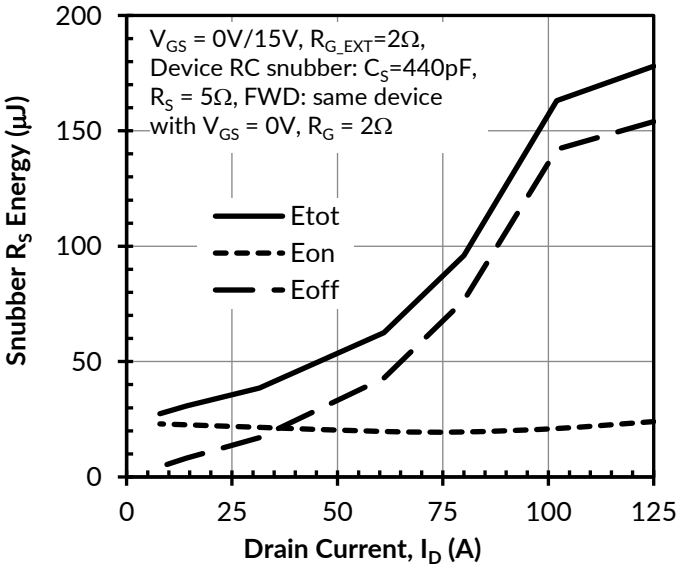


Figure 20. RC snubber energy loss vs. drain current at V_{DS} = 800V and T_J = 25°C

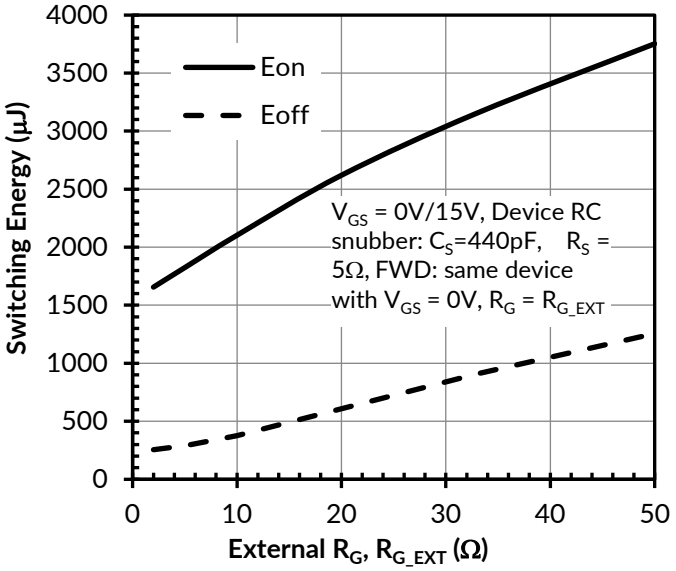


Figure 21. Clamped inductive switching energies vs. $R_{G,EXT}$ at V_{DS} = 800V, I_D = 80A, and T_J = 25°C

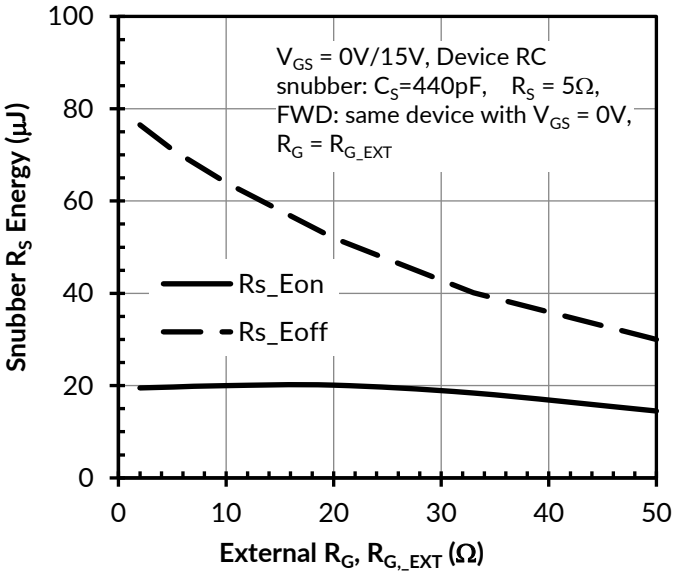


Figure 22. RC snubber energy losses vs. $R_{G,EXT}$ at V_{DS} = 800V, I_D = 80A, and T_J = 25°C

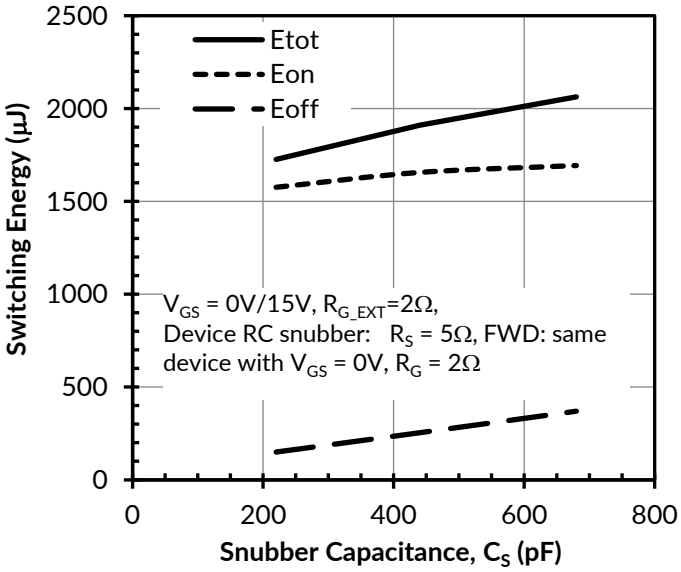


Figure 23. Clamped inductive switching energies vs. snubber capacitance C_S at V_{DS} = 800V, I_D = 80A, and T_J = 25°C

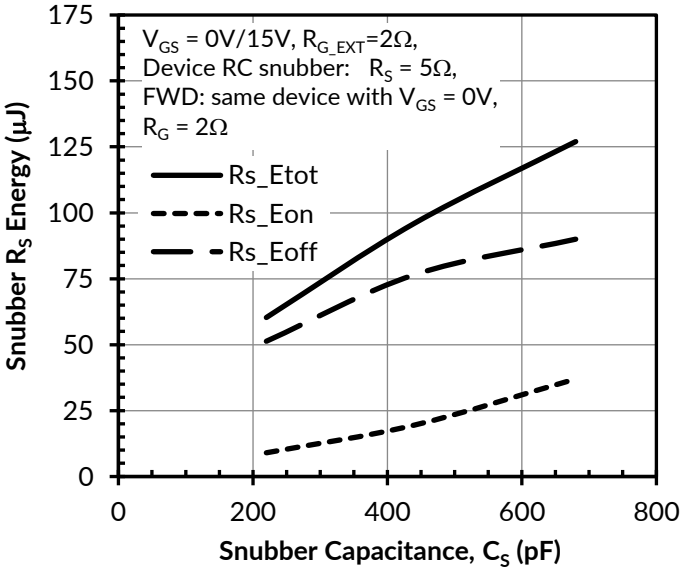


Figure 24. RC snubber energy losses vs. snubber capacitance C_S at V_{DS} = 800V, I_D = 80A, and T_J = 25°C

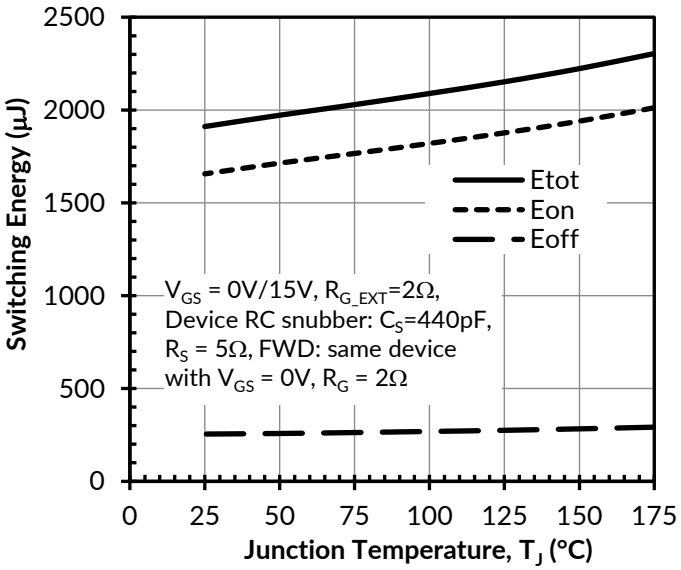


Figure 25. Clamped inductive switching energy vs. junction temperature at V_{DS} =800V and I_D = 80A

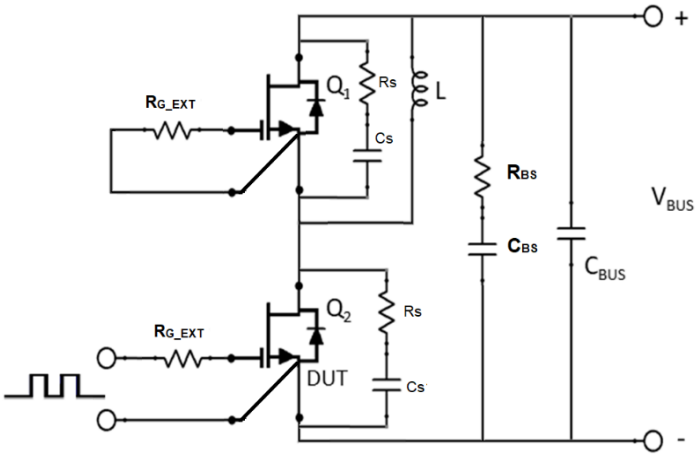


Figure 26. Schematic of the half-bridge mode switching test circuit. Note, a bus RC snubber (R_{BS} = 5Ω, C_{BS}=100nF) is used to reduce the power loop high frequency oscillations.

Applications Information

SiC FETs are enhancement-mode power switches formed by a high-voltage SiC depletion-mode JFET and a low-voltage silicon MOSFET connected in series. The silicon MOSFET serves as the control unit while the SiC JFET provides high voltage blocking in the off state. This combination of devices in a single package provides compatibility with standard gate drivers and offers superior performance in terms of low on-resistance ($R_{DS(on)}$), output capacitance (C_{oss}), gate charge (Q_G), and reverse recovery charge (Q_{rr}) leading to low conduction and switching losses. The SiC FETs also provide excellent reverse conduction capability eliminating the need for an external anti-parallel diode.

Like other high performance power switches, proper PCB layout design to minimize circuit parasitics is strongly recommended due to the high dv/dt and di/dt rates. An external gate resistor is recommended when the FET is working in the diode mode in order to achieve the optimum reverse recovery performance. For more information on SiC FET operation, see https://www.qorvo.com/innovation/power-solutions/sic-power/sic-fet-design-tips.

A snubber circuit with a small $R_{(G)}$, or gate resistor, provides better EMI suppression with higher efficiency compared to using a high $R_{(G)}$ value. There is no extra gate delay time when using the snubber circuitry, and a small $R_{(G)}$ will better control both the turn-off $V_{(DS)}$ peak spike and ringing duration, while a high $R_{(G)}$ will damp the peak spike but result in a longer delay time. In addition, the total switching loss when using a snubber circuit is less than using high $R_{(G)}$, while greatly reducing $E_{(OFF)}$ from mid-to-full load range with only a small increase in $E_{(ON)}$. Efficiency will therefore improve with higher load current. For more information on how a snubber circuit will improve overall system performance, visit the Qorvo website at https://www.qorvo.com/innovation/power-solutions/sic-power/sic-fet-design-tips.

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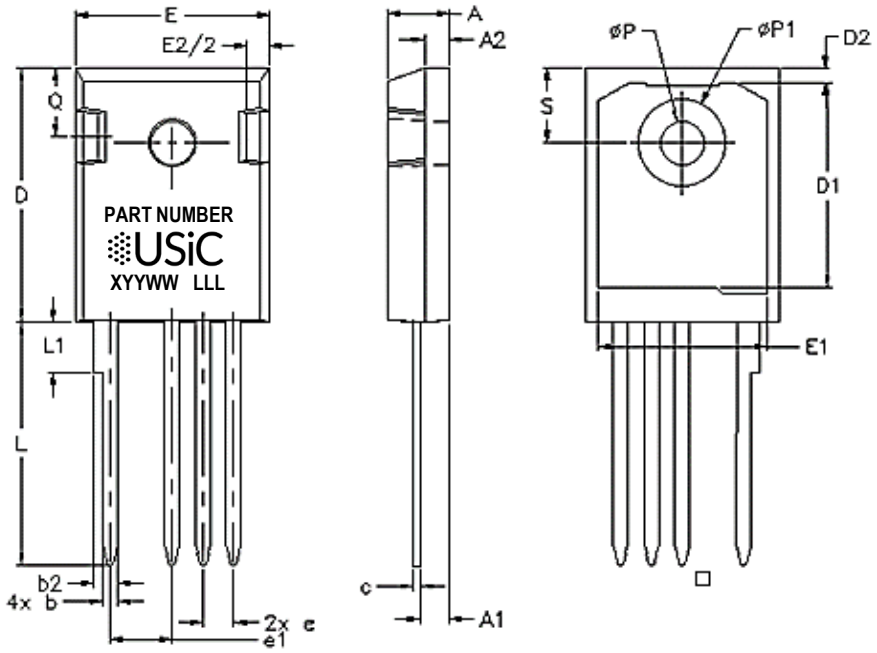
TO-247-4L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

PACKAGE OUTLINE



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.185	0.209	4.7	5.31
A1	0.087	0.102	2.21	2.59
A2	0.059	0.098	1.5	2.49
b	0.039	0.055	0.99	1.4
b2	0.065	0.094	1.65	2.39
c	0.015	0.035	0.38	0.89
D	0.819	0.845	20.8	21.46
D1	0.515	-	13.08	-
D2	0.02	0.053	0.51	1.35
E	0.61	0.64	15.49	16.26
e	0.100 BSC		2.54 BSC	
e1	0.19	0.21	4.83	5.33
E1	0.53	-	13.46	-
E2	0.14	0.16	3.56	4.06
L	0.78	0.8	19.81	20.32
L1	-	0.177	-	4.5
ΦP	0.14	0.144	3.56	3.66
ΦP1	0.278	0.291	7.06	7.39
Q	0.212	0.244	5.38	6.2
S	0.243 BSC		6.17 BSC	

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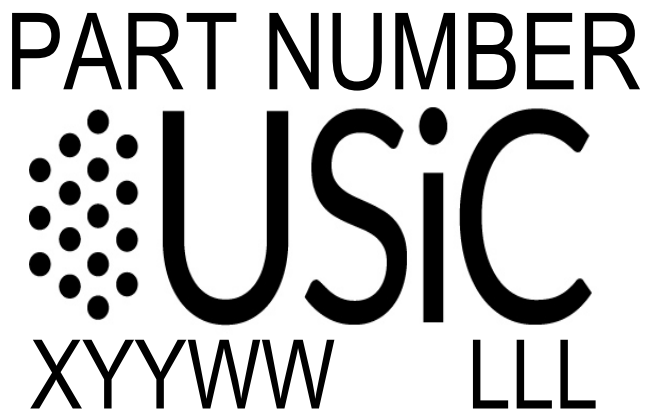
PART MARKING



PART NUMBER = REFER TO DS_PN DECODER FOR DETAILS

X = ASSEMBLY SITE
YY = YEAR
WW = WORK WEEK
LLL = LOT ID

PACKING TYPE

ANTI-STATIC TUBE

QUANTITY /TUBE : 30 UNITS

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